Package Outline
HEXFET SO-8 Outline
Dimensions are shown in millimeters (inches)

NOTES:
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (0.06).
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (0.10).
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

FOOTPRINT

DIM | INCHES      | MILLIMETERS |
----|-------------|-------------
A   | 0.0532-0.0688 | 1.35-1.75   |
A1  | 0.0040-0.0098 | 0.10-0.25   |
b   | 0.013-0.020   | 0.33-0.51   |
c   | 0.0075-0.0098 | 0.19-0.25   |
D   | 0.189-0.1968  | 4.80-5.00   |
E   | 0.147-0.1574  | 3.80-4.00   |
e   | 0.050 BASIC   | 1.27 BASIC  |
e1  | 0.025 BASIC   | 0.635 BASIC |
H   | 0.2284-0.2440 | 5.80-6.20   |
K   | 0.0099-0.0196 | 0.25-0.50   |
L   | 0.016-0.050   | 0.40-1.27   |
y   | 0°-8°        | 0°-8°       |

K x 45°